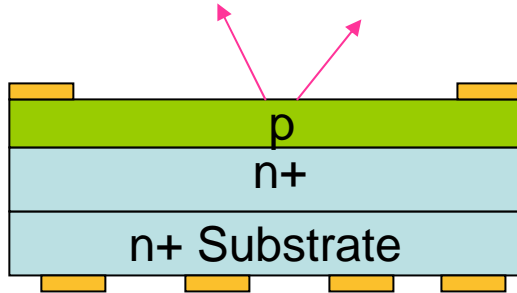
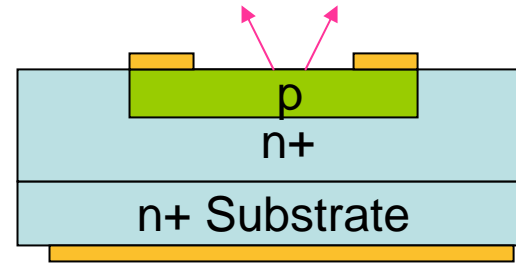


LED structure

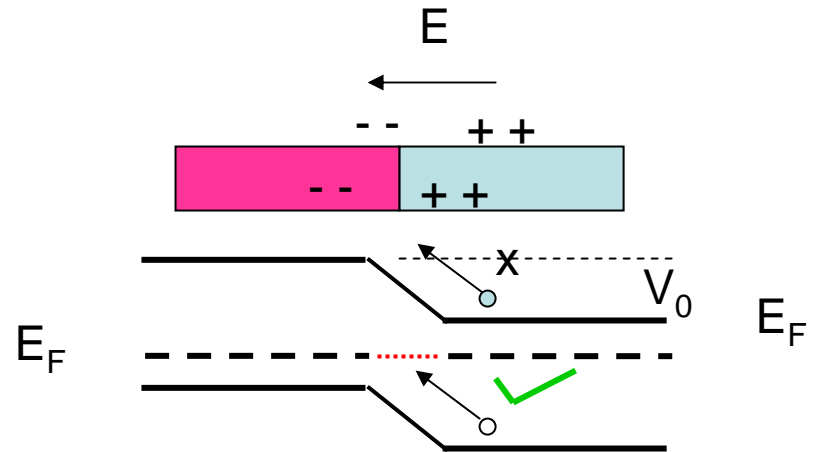
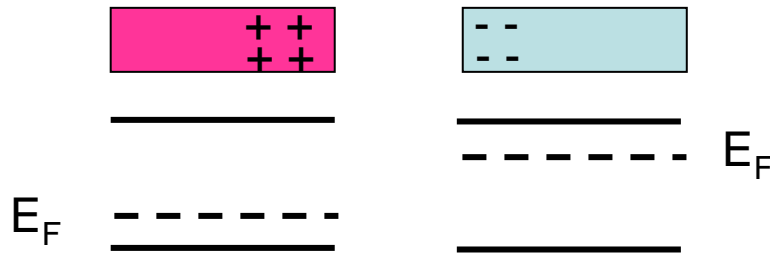


Epitaxial LED



Diffusion LED

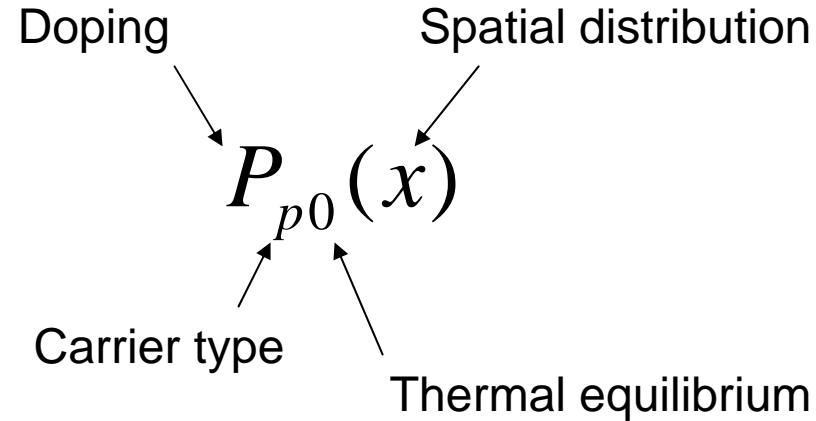
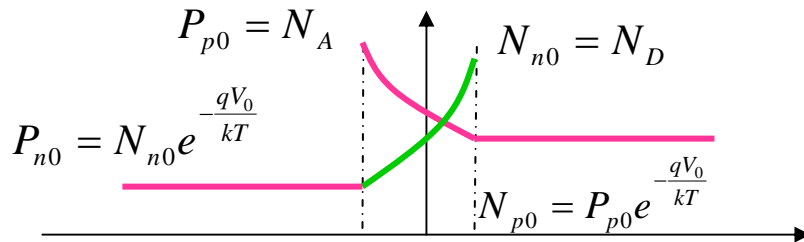
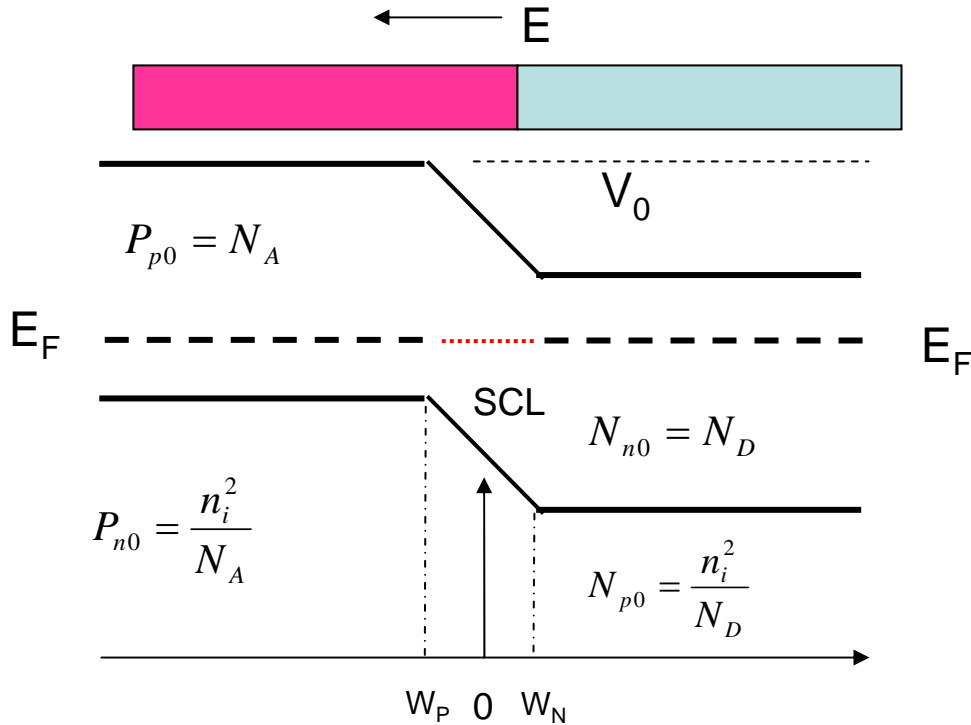
Band diagram



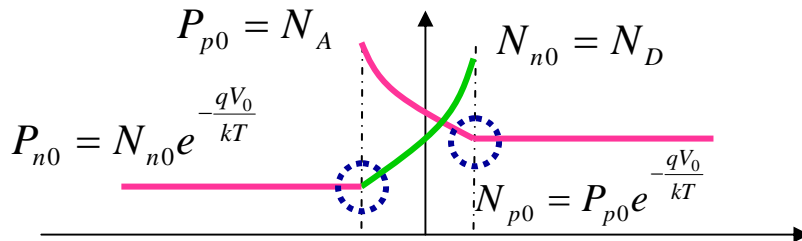
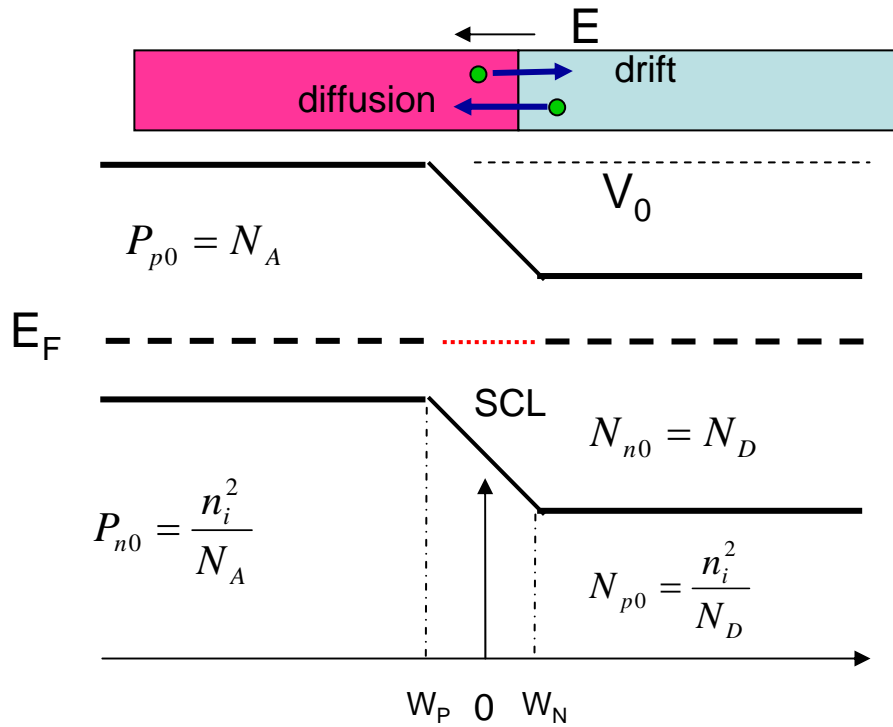
$$E_F - E_i = -\frac{kT}{q} \ln\left(\frac{n_i}{N_D}\right) \quad E_i - E_F = \frac{kT}{q} \ln\left(\frac{n_i}{N_A}\right)$$

$$V_0 = \frac{kT}{q} \ln\left(\frac{N_A N_D}{n_i^2}\right)$$

Carrier concentration



$$V_0 = \frac{kT}{q} \ln\left(\frac{N_A N_D}{n_i^2}\right)$$



Net J out and in = 0

$$J_{drift} = n_0 \mu_e E = 0$$

$$J_{diffusion} = 0 \quad \text{Why?}$$

$$\rightarrow J_{diffusion} = eD \frac{\partial n_0}{\partial x}$$

$$\leftarrow J_{drift} = n_0 \mu_e E$$

$$J_{drift} = J_{diffusion} \Rightarrow n_0 \mu_e E = D_e \frac{\partial n_0}{\partial x}$$

$$\Rightarrow \frac{dn_0}{n_0} = (\mu_e / D_e) E dx$$

$$\Rightarrow d \ln(n) = -(\mu_e / D_e) dV$$

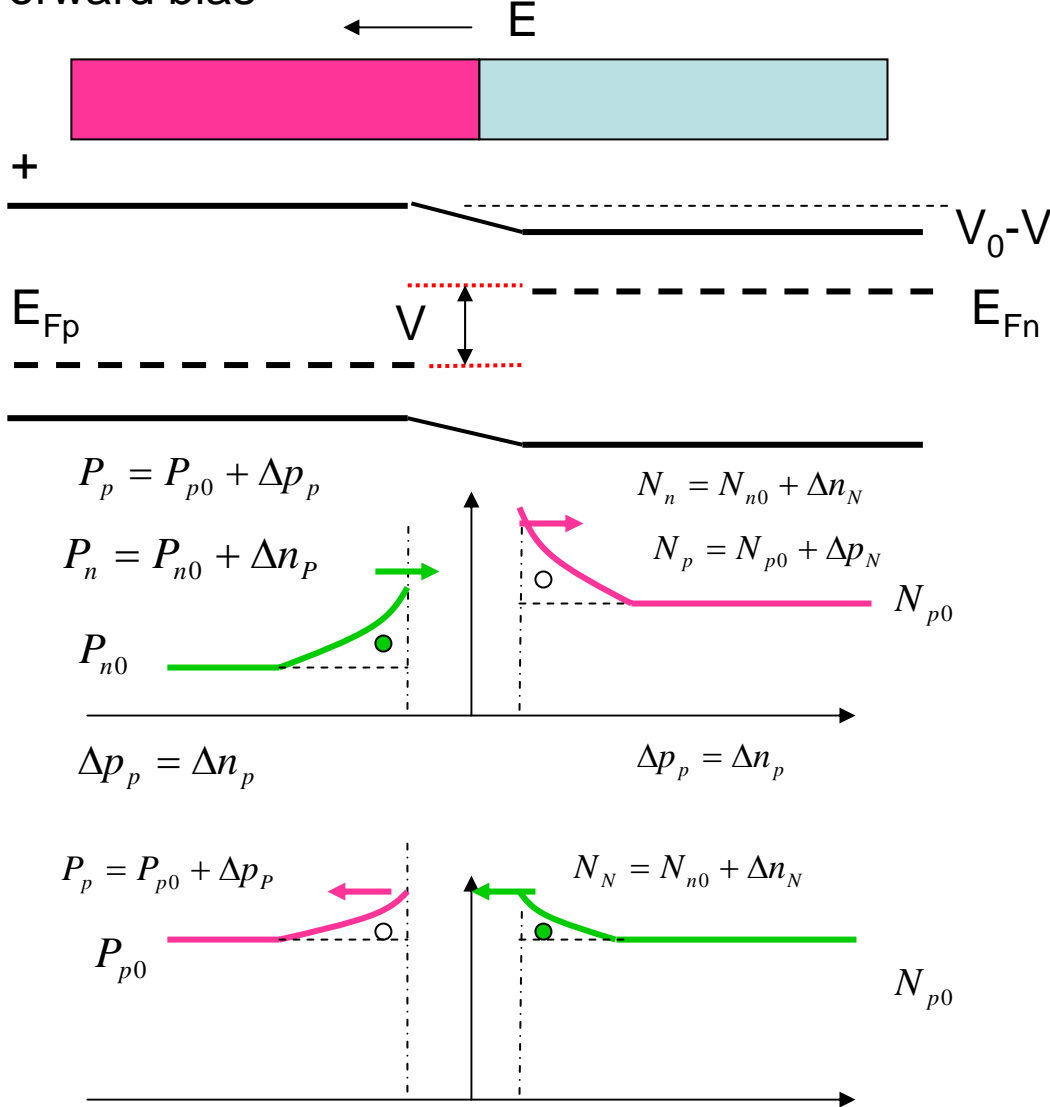
$$\Rightarrow \ln(n / n(0)) = -[V(W) - V(0)] = -V_0$$

$$\Rightarrow n(W) = n(0) e^{-\frac{qV_0}{kT}}$$

$$\Rightarrow n(x) = n(0) e^{-\frac{qV(x)}{kT}}$$

$$p(x) = p(0) e^{-\frac{qV(x)}{kT}}$$

Forward bias



Δp_p Excess hole on the P side

$$n(x) = n(0)e^{\frac{qV(x)}{kT}} \quad n(x) = n(0)e^{\frac{q(V_0-V)}{kT}}$$

$$P_n = n(0) = N_n e^{-\frac{qV_0}{kT}} e^{\frac{qV}{kT}}$$

$$P_{n0} = N_{n0} e^{-\frac{qV_0}{kT}}$$

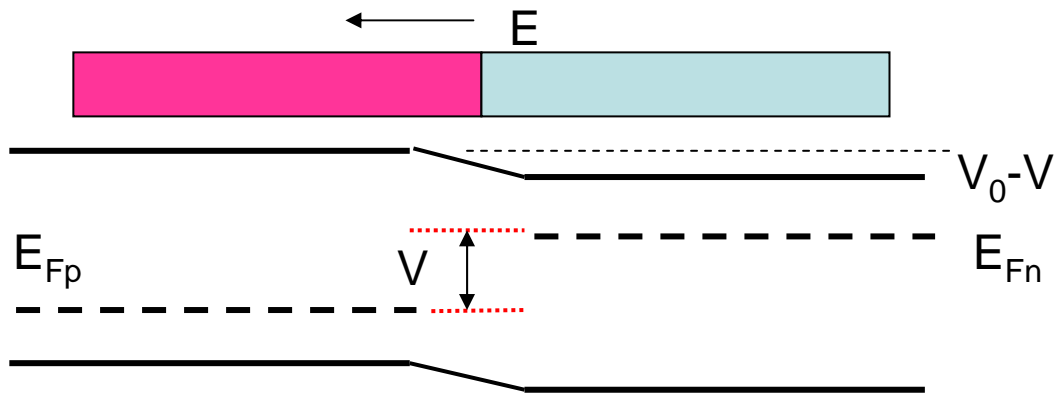
$$\Delta n_p = P_{n0} \left(e^{\frac{qV}{kT}} - 1 \right)$$

$$\Delta p_N = N_{p0} \left(e^{\frac{qV}{kT}} - 1 \right)$$

Weak injection $\Delta p_p = \Delta n_p = P_{n0} e^{\frac{qV}{kT}} \ll P_{p0}$

Strong injection $\Delta p_p = \Delta n_p = P_{n0} e^{\frac{qV}{kT}} \sim P_{p0}$

Ignore majority carrier diffusion at weak injection, why?



$$\nabla \cdot \vec{J} = -q \frac{\partial \Delta n}{\partial t}$$

No drift current, why?

$$\frac{\partial J}{\partial x} = -q \frac{\partial \Delta n}{\partial t}$$

$$J_{diffusion} = qD \frac{\partial \Delta n}{\partial x}$$

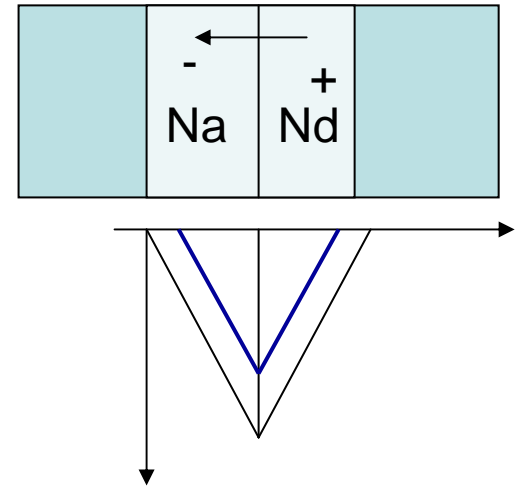
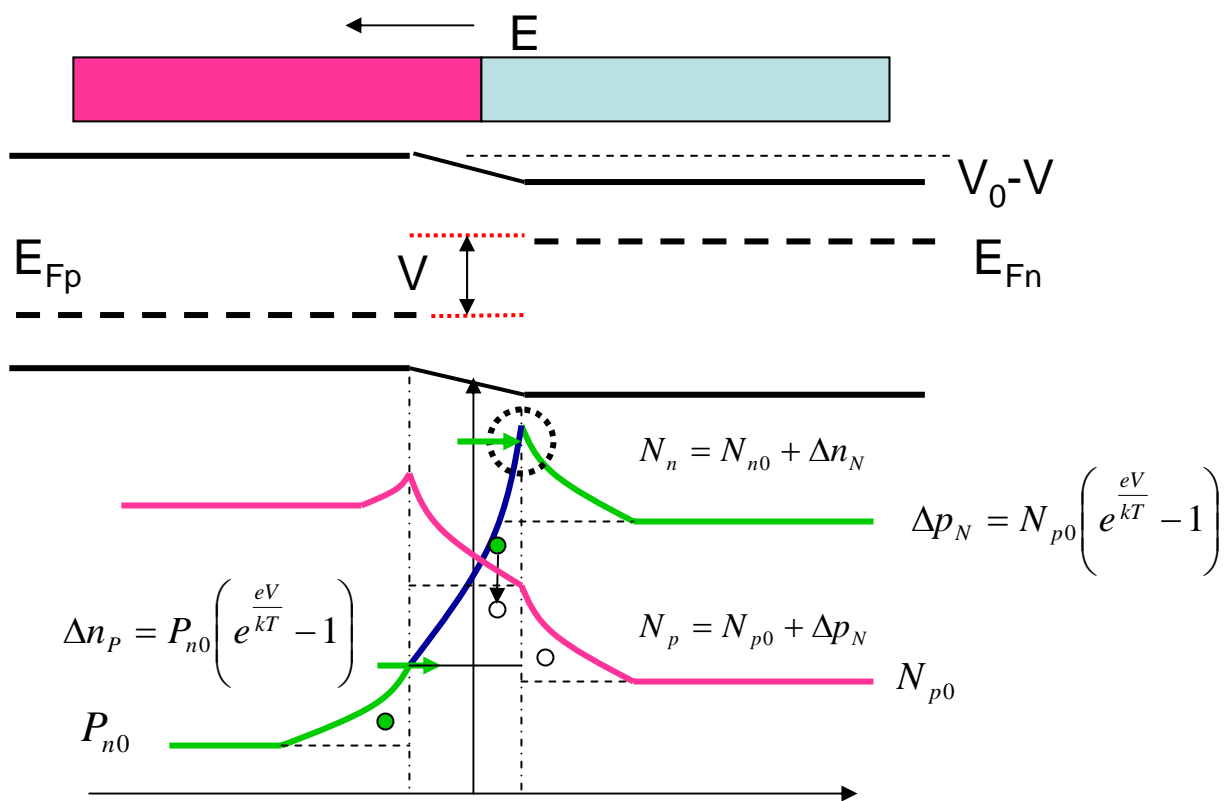
$$D \frac{\partial^2 \Delta n}{\partial x^2} = \frac{\Delta n}{\tau_p}$$

$$\Delta n(x, t) = \Delta n(x = -W_p, t) e^{x/L_n} \quad L_n = \sqrt{D_n \tau_n}$$

$$\Delta p(x, t) = \Delta p(x = W_n, t) e^{-x/L_p} \quad L_p = \sqrt{D_p \tau_p}$$

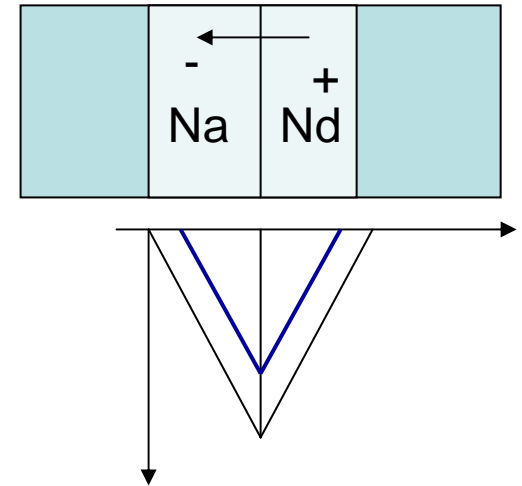
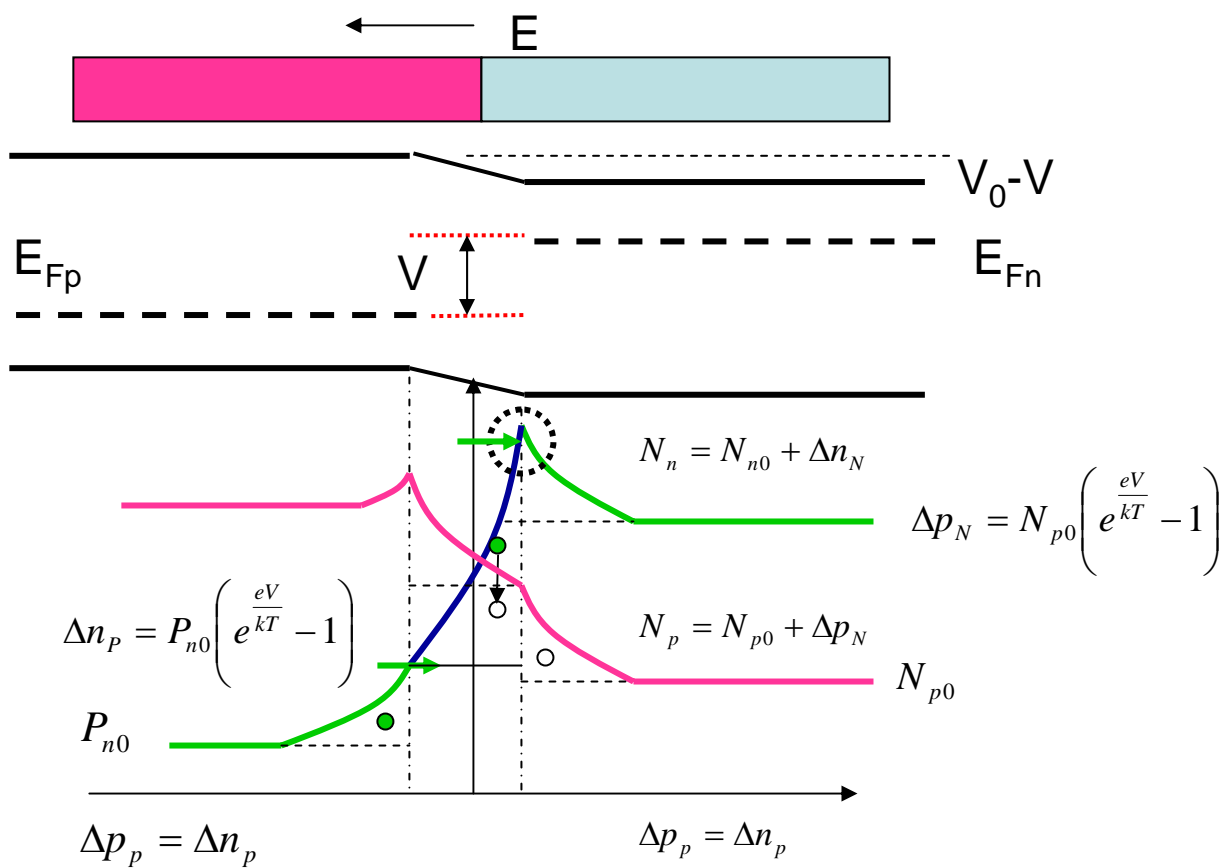
$$J_n |_{x=-W_p} = qD_n \frac{d\Delta n}{dx} |_{x=-W_p} = \frac{qD_n}{L_n} n_{p,0} (e^{\frac{qV}{kT}} - 1) = \frac{qD_n}{L_n} \frac{n_i^2}{N_A} (e^{\frac{qV}{kT}} - 1)$$

$$J_p |_{x=W_n} = qD_p \frac{d\Delta p}{dx} |_{x=W_n} = \frac{qD_p}{L_p} N_{p,0} (e^{\frac{qV}{kT}} - 1) = \frac{qD_p}{L_p} \frac{n_i^2}{N_D} (e^{\frac{qV}{kT}} - 1)$$



$$J_r = \left(\frac{qn_i W}{2\tau_n} + \frac{qn_i W}{2\tau_p} \right) \left(e^{\frac{qV}{2kT}} - 1 \right)$$

$$\Delta n = \frac{N_{n0} W}{2} \left(e^{-q \frac{V_0 - V}{2kT}} - 1 \right) \approx \frac{n_i W}{2} \left(e^{\frac{qV}{2kT}} - 1 \right)$$



$$J_n = \frac{qD_n}{L_n} \frac{n_i^2}{N_A} \left(e^{\frac{qV}{kT}} - 1 \right)$$

$$J_p = \frac{qD_p}{L_p} \frac{n_i^2}{N_D} \left(e^{\frac{qV}{kT}} - 1 \right)$$

$$J_r = \left(\frac{qn_i W}{2\tau_n} + \frac{qn_i W}{2\tau_p} \right) \left(e^{\frac{V}{\eta kT}} - 1 \right)$$

1. Radiative combination \longrightarrow Emit light

2. non-radiative combination \longrightarrow Emit heat

on P side:

$$n_p = n_{p0} + \Delta n_p \quad \leftarrow \begin{array}{l} \text{instantaneous} \\ \text{minority carriers} \end{array}$$

$$P_p = P_{p0} + \Delta P_p \quad \leftarrow \text{majority carriers}$$

$$\begin{aligned} \frac{\partial n_p}{\partial t} &= -B n_p P_p + G_{\text{thermal}}, \quad B \text{ is direct recombination coefficient} \\ &= -B (n_p P_p - n_{p0} P_{p0}) \\ &= -B (n_{p0} + \Delta n_p)(P_{p0} + \Delta P_p) + B n_{p0} P_{p0}. \end{aligned}$$

at low injection level: $\Delta n_p \ll P_{p0}$ $\approx -B \Delta n_p P_{p0} = -B \Delta n_p \cdot N_a$

$$\frac{\partial \Delta n_p}{\partial t} = -\frac{n_p}{\tau_c} \Rightarrow \tau_c = \frac{1}{B N_a} \sim ns$$

at high injection level: $\Delta n_p \gg P_{p0}$

$$\frac{\partial \Delta n_p}{\partial t} = -B \Delta n_p \cdot \Delta P_p = -B (\Delta n_p)^2$$

$$\tau_c = \frac{1}{B \Delta n_p}$$

Recombination coefficients of Representative Semiconductors

Material	Bandgap type	B_r
Si	indirect	$1.79 \times 10^{-15} \text{ cm}^3/\text{s}$
Ge	indirect	$5.25 \times 10^{-14} \text{ cm}^3/\text{s}$
GaP	indirect	$5.37 \times 10^{-14} \text{ cm}^3/\text{s}$
GaAs	direct	$7.21 \times 10^{-10} \text{ cm}^3/\text{s}$
GaSb	Direct	$2.39 \times 10^{-10} \text{ cm}^3/\text{s}$
InAs	Direct	$8.5 \times 10^{-11} \text{ cm}^3/\text{s}$
InSb	Direct	$4.58 \times 10^{-11} \text{ cm}^3/\text{s}$

What lifetime implies?

Modulation bandwidth for lifetime $\sim \text{ns}$
 Maximum modulation $\sim \text{GHz}$

Example : calculate radiative lifetime of GaAs & Si

1). GaAs, assuming low level injection:

$$p \sim 10^{18} \text{ cm}^{-3} \leftarrow N_A$$

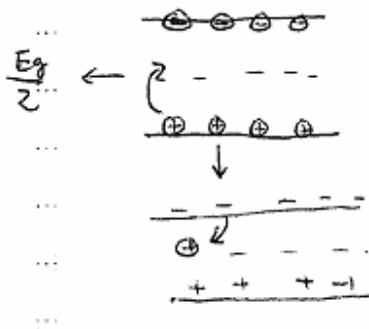
$$\tau_r = \frac{1}{B r p} = \frac{1}{B r N_A} = \frac{1}{7.2 \times 10^{-10} \cdot 10^{18}} = 1.4 \text{ ns.}$$

2). Si,

$$p \sim 10^{18} \text{ cm}^{-3} \leftarrow N_A$$

$$\tau_r = \frac{1}{B r N_A} = \frac{1}{1.8 \times 10^{-15} \cdot 10^{18}} = 0.6 \text{ ms}$$

non-radiative combination



- 1). electron-hole pairs "recombine" through traps in the forbidden gap, which emit heat or multi-phonons also called space-charge recombination, which is a two-step process.

the Non-radiative recombination rate in space charge region

$$R = \frac{n_i}{2\tau} e^{2V/2KT}, \quad \tau = \frac{1}{\sigma_t v_{th} N_t}$$

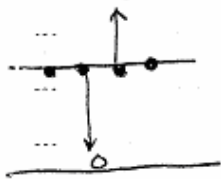
$\sigma_t := \sigma_p = \sigma_n \equiv$ hole & electron capture cross section

$\sigma_p = \sigma_n$, since trap is at roughly $\frac{E_A}{2}$.

v_{th} : thermal velocity.

N_t : density of traps

2) Auger recombination



collision of two electrons which knocks one electron down to valance band and the other to a higher energy state in CB.

$$\tau_A = \frac{1}{C n_0^2}, \quad R_A = C n^3$$

Auger recombination is important only at high injection level, τ is material dependent

example, GaAs, $\tau = 5 \times 10^{-30} \text{ cm}^6/\text{s}$.

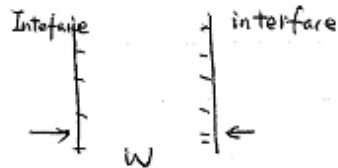
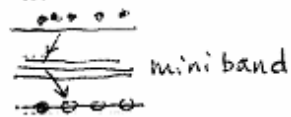
InGaAsP, $\tau = 10^{-28} \text{ cm}^6/\text{s}$.

For $n_0 = 5 \times 10^{17} \text{ cm}^{-3}$, GaAs $\tau_A = \frac{1}{5 \times 10^{-30} \cdot (5 \times 10^{17})^2} = 8 \mu\text{s}$

InGaAsP $\tau_A = \frac{1}{10^{-28} \cdot (5 \times 10^{17})^2} \approx 40 \text{ (ns)}$.

3) Interface Recombination

- dangling bonds at surface and material interface which forms miniband in Energy gap



$$\tau_s = \frac{W}{2S}$$

$S \equiv$ interface recombination velocity

typical value of S :

$$\text{GaAs} \sim 10^6 \text{ cm/s}$$

$$\text{InP} \sim 10^3 \text{ cm/s}$$

heterojunction interface

$$\text{Si/SiO}_2 \sim 10 \text{ cm/s}$$

$$\text{GaAs/AlGaAs} \sim 500 \text{ cm/s}$$

recently reduced to

$$\text{InP/InGaAsP} \sim \begin{matrix} 0.25 \text{ cm/s} \\ 10^3 - 10^4 \end{matrix}$$

Quantum Efficiency (QE)

1. internal QE. $\eta_i = \frac{\# \text{ of photons generated}}{\# \text{ electron-hole injected}}$

$$\eta_i = \frac{R_r}{R_{\text{total}}} = \frac{\frac{\Delta n}{\tau_r}}{\frac{\Delta n}{\tau_n} + \frac{\Delta n}{\tau_p}} = \frac{\frac{1}{\tau_r}}{\frac{1}{\tau_r} + \frac{1}{\tau_{nr}}} = \frac{1}{1 + \frac{\tau_r}{\tau_{nr}}}$$

$$R_{\text{total}} = R_r + R_{nr} = R_r + R_t + R_A + R_S$$

$$= \frac{1}{\tau_r} \Delta n + \frac{1}{\tau_t V_{th} n_0} \Delta n + \frac{\Delta \tau}{C n_0^2} + \frac{\Delta n}{\tau_s}$$

Example: η_i for GaAs \gg Si:

GaAs: $\tau_r \sim 1 \text{ ns}$, Assuming Interface recombination dominates.

$$S = 500 \text{ cm/s}, \quad W \sim 0.3 \times 10^{-4} \text{ mm}, \quad \Rightarrow \tau_{nr} = 30 \text{ ns}$$

$$\eta_i \sim 97\%$$

For Si, $\tau_r = 2 \times 10^{-4} \text{ s}$, $\tau_{nr} \approx 100 \text{ ns}$.

$$\eta_i \sim 5 \times 10^{-4}$$

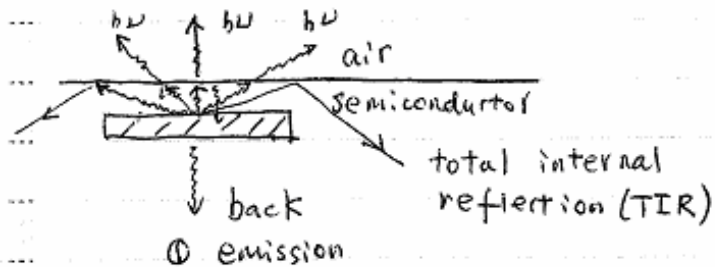
Conclusion: ① τ_r needs to be small enough.

② Si is not a good light emitter.

External Quantum Efficiency

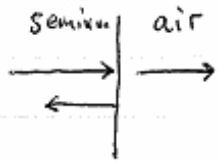
$$\eta_e = \frac{\# \text{ photons emitted}}{\# \text{ eHP injected}}$$

← depends on η_i and device structure



① back emission $\sim 50\%$ Loss through back

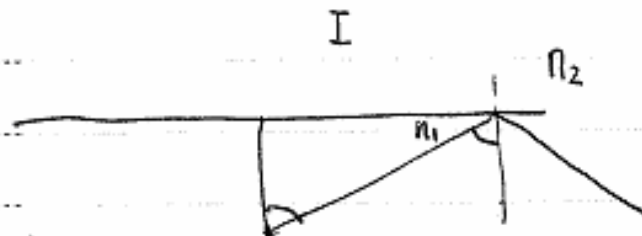
② Fresnel Reflection:



$$r = \frac{n_1 - n_2}{n_1 + n_2} = \frac{3.5 - 1}{3.5 + 1} = \frac{2.5}{4.5} = 40\%$$

③ Reabsorption:

④ total internal reflection

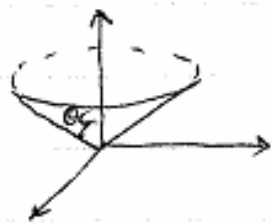


$$n_1 \sin \theta_1 = n_2 \sin \theta_2$$

$$\Rightarrow \sin \theta_c = \frac{n_2}{n_1} \sin \theta_2 \quad \theta_2 = 90^\circ$$

• Lambert Law: Light measured will vary as the cosine of the angle off normal $\Rightarrow \theta_c \sim 16^\circ$

any light generated in the active region that larger than $\theta_c = 16^\circ$, will not be emitted



efficiency due to TIR

$$\frac{P_{out}}{P_{in}} = \frac{\int_0^{\theta_c} \sin \theta \, d\theta \, 2\pi}{\int_0^{\pi/2} \sin \theta \, d\theta \, 2\pi} = \frac{1}{2} \frac{\sin^2 \theta_c}{1} = \frac{1}{2} \left(\frac{n_2}{n_1} \right)^2$$

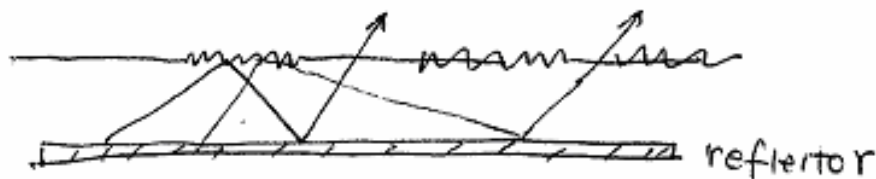
include Fresnel reflections:

$$\frac{P_{out}}{P_{in}} = (1-R) \cdot \frac{1}{2} \sin^2 \theta_c = 3\% \quad \leftarrow \text{Low Quantum efficiency}$$

↑ ~~fundamental~~ fundamental Problem of LED for 35 years.

Solution:

- textured structure



- Grating

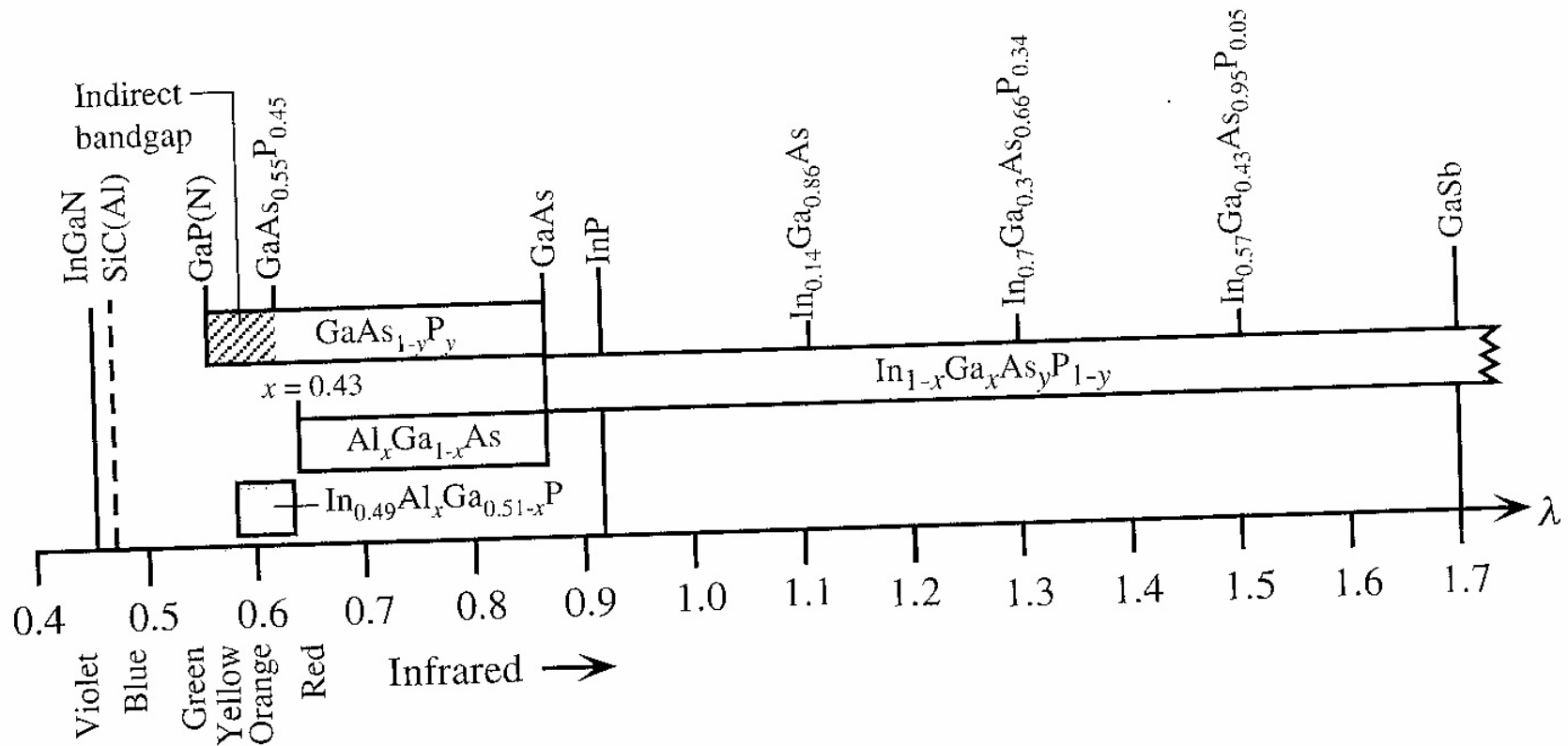
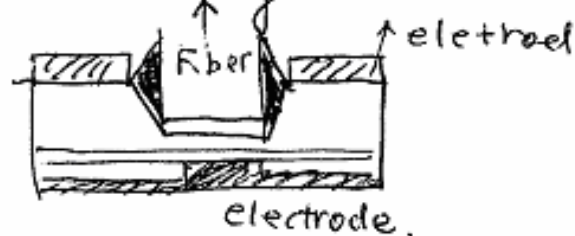
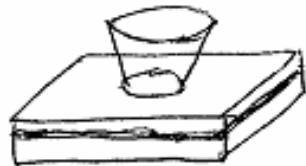


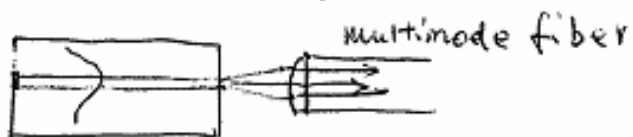
FIGURE 3.25 Free space wavelength coverage by different LED materials from the visible spectrum to the infrared including wavelengths used in optical communications. Hatched region and dashed lines are indirect E_g materials.

Communication LEDs

1. Structure: a). surface emitting



b). edge emitting



- high coupling efficiency

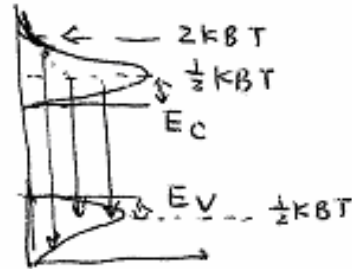
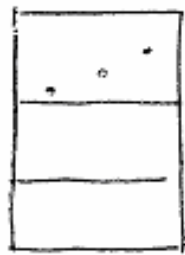
- very thin active layer

⇒ much of the light extends to cladding layer. ⇒ low reabsorption

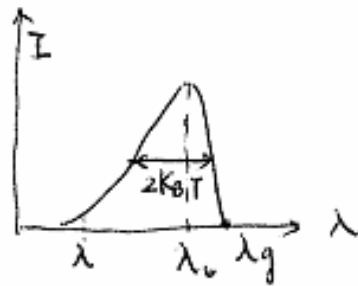
- AR coating front facet
- HR coating back facet.

2. Emission Spectra

2. Emission spectra



- electron & hole peaks
at $\frac{1}{2}k_B T + E_C$
& $-\frac{1}{2}k_B T + E_V$
width $\sim 2k_B T$



$$\lambda \cdot \nu = \frac{c}{n}$$

- $(h\nu)_{\text{peak}} = E_g + k_B T$
- $\Delta h\nu = 2k_B T$

$$\lambda = \frac{c}{\nu n}$$

$$\Rightarrow \Delta \lambda = \frac{c}{-\nu^2 n} \Delta \nu = -\frac{\lambda_0^2}{hc/n} \Delta(h\nu)$$

$$= -\frac{\lambda^2}{hc/n} \cdot 2k_B T$$

- $\Delta\lambda \propto \lambda_0^2$

$$\frac{\Delta\lambda_{\text{InGaAs}} (\sim \lambda \sim 1.3 \mu\text{m})}{\Delta\lambda_{\text{GaAs}} (\lambda \sim 0.85 \mu\text{m})} = 2.3$$

a). GaAs $\lambda_0 \sim 0.85 \mu\text{m}$, $\Delta\lambda = 300 \text{ \AA} = 30 \text{ nm}$

b). InGaAsP $\lambda_0 \sim 1.08 \mu\text{m}$, $\Delta\lambda \approx 500 \text{ \AA}$

c). InGaAsP, $\lambda \sim 1.3 \mu\text{m}$, $\Delta\lambda \approx 700 \text{ \AA}$

- $\Delta\lambda$ increases with N_a

- $\Delta\lambda$ increase as injection level increase

Examples:

1. LED output wavelength variations

Consider, GaAs LED, $E_g = 1.42 \text{ eV}$ @ 300K.

$$\frac{dE_g}{dT} = -4.5 \times 10^{-4} \text{ eV/K. find } \frac{d\lambda}{dT}.$$

$$(h\nu)_{\text{peak}} = E_g + k_B T \Rightarrow h \cdot \frac{c}{n\lambda} = E_g + k_B T$$

$$\Rightarrow \frac{hc}{n(E_g + k_B T)} = \lambda \Rightarrow \frac{d\lambda}{dT} = -\frac{hc}{n} \cdot \frac{dE_g/dT}{(E_g + k_B T)^2}$$

$$= 2.8 \times 10^{-10} \text{ m/K} = 0.28 \text{ nm/K}$$

2. The ternary alloy $\text{In}_{1-x}\text{Ga}_x\text{As}_y\text{P}_{1-y}$

to avoid lattice mismatch, $y \approx 2.2x$.

$$E_g = 1.35 - 0.72y + 0.12y^2, \quad 0.05x \leq 0.47$$

calculate the composition of InGaAsP to make the emission peak at $1.3 \mu\text{m}$

$$(h\nu)_{\text{peak}} = E_g + k_B T \Rightarrow \frac{hc}{n\lambda} = E_g + k_B T$$

$$\lambda = 1.3 \mu\text{m}$$

$$\Rightarrow E_g = 0.928 \text{ eV} = 1.35 - 0.72y + 0.12y^2$$

$$\Rightarrow y = 0.66 \Rightarrow x = \frac{y}{2.2} = 0.3$$

$$\text{In}_{0.7}\text{Ga}_{0.3}\text{As}_{0.66}\text{P}_{0.34}$$

3. Bandwidth, (modulation Bandwidth)

... wide bandwidth \Rightarrow require shorter carrier lifetime

... why?
 $I(\omega) = \frac{I_{dc}}{\sqrt{1+(\omega\tau)^2}}$, $P \propto I(\omega)^2$

... $P_{3dB} = \frac{P_{dc}}{2} \Rightarrow \omega\tau = 1$, $f_{3B} = \frac{1}{2\pi\tau}$

... \Rightarrow short τ_{cr} .

... $\frac{1}{\tau} = \frac{1}{\tau_r} + \frac{1}{\tau_{nr}}$, $\tau_r = \frac{1}{N_a B_r}$ at low injection

... $\Rightarrow f_{3B} = \frac{B_r N_a}{2\pi}$, independent of current at low injection.

at high injection:

... $\tau_r = \frac{1}{B_r \Delta n_p}$, $J = \frac{qW\Delta n}{\tau} \Rightarrow \Delta n = J\tau/qW$

... $\Rightarrow (\tau_r)^{-1} = \left(\frac{B_r J}{qW}\right)^{1/2}$

... $\Rightarrow f_{3B} = \frac{1}{2\pi} \left(\frac{B_r J}{qW}\right)^{1/2}$

4. Bandwidth \leftrightarrow output Power trade off

a) at low injection:

... $f_{3B} = \frac{B_r N_a}{2\pi}$, $N_a \uparrow \Rightarrow f_{3B} \uparrow$

however, heavy doping ($> 10^{18} \text{cm}^{-3}$) forms

Nonradiative recombination centers, $\tau_{nr} \downarrow$

e.g. @ $N_a \sim 2 \times 10^{19} / \text{cm}^3$, $\tau_r = 1 \text{ ns}$, $\tau_{nr} \approx 1 \text{ ns}$

... $\eta_i = \frac{1}{1 + \tau_r/\tau_{nr}} = 50\%$

b). at high injection

$$f_{3B} = \frac{1}{2\pi} \left(\frac{BrJ}{qW} \right)^{1/2}$$

reduce W , can increase f_{3B}

but increase interface recombination

e.g. GaAs

$$\tau_r = 10 \text{ ns}, \quad S = 300 \text{ cm/s}, \quad W = 2 \mu\text{m}$$

$$\tau_{nr} = \frac{W}{2S} \approx 200 \text{ ns}$$

$$\Rightarrow \tau = 9.5 \text{ ns} \Rightarrow f_{3B} = 37 \text{ MHz}, \quad \eta_i \approx 100\%$$

if $W = 0.1 \mu\text{m}$

$$\tau_{nr} = 10 \text{ ns}, \quad \tau = 5 \text{ ns}, \quad f_{3dB} = 200 \text{ MHz}$$

$$\eta_i = 50\%$$

5. applications of communication LED

a). surface emitters

- large volume, low-cost arrays
- on wafer testing
- chip-to-chip optical interconnects

b). Edge emitters

short distance fiber optic communication.